

Specification SSC-FCW302

SSC		Customer
Drawn	Approval	Approval



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1. Features

- Package : 3.5 imes 2.8 imes 0.85 mm
- Applications : Mobile Handset Flash Light

2. Absolute maximum ratings

(Ta=25℃) Symbol Value **Parameter** Unit **Power Dissipation** P_d 1020 mW **Forward Current** I_{F} 300 mΑ $I_{\rm FM}$ *1 **Peak Forward Current** 1000 mΑ V_R 5 V **Reverse Voltage** -30 ~ 80 T_{opr.} **Operation Temperature** °C **Storage Temperature** T_{stg.} -40 ~ 100 °C

*1 $~I_{FM}$ conditions: Pulse width Tw≤300ms and Duty ratio≤1/10 ~

3. Electro-Optical Characteristics

Symbol Unit Parameter Condition Min Max Тур **Forward Voltage** VF I_=300mA _ 3.4 _ V **Zener Forward Voltage** I_=10mA 1.5 V $V_{F(z)}$ 0.6 - $I_F = 300 \text{ mA}$ 48 60 FCW302A $I_{F}=1000 \text{ mA}$ 130 160 -(Flash mode)² Luminous Flux^{*1} L_{F} Im $I_{\text{F}}=300 \text{ mA}$ 79 63 -FCW302B I_F=1000 mA 180 190 -(Flash mode)² Х I_=300 mA 0.3226 --Chromaticity Coordinates Y I_F=300 mA 0.3306 5900 **Color Temperature** I_=300 mA _ _ Κ ССТ 0 20_{1/2} 120 Viewing Angle I=300mA --

*1 Luminous Flux is measured in integrating sphere

*2 Flash mode is Pulse width Tw \leq 300ms, Duty Ratio 1/10

[Note] (Tolerance : IV \pm 10%, color coordinate \pm 0.01, VF \pm 0.1)

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(Ta=25℃)





Forward Current vs. Forward Voltage

Luminous Intensity vs. Forward Current





Forward Current Derate Curve

Forward Current vs. Chromaticity Coordinate



0.345 0.340 0.345 0.340 0.325 0.320 0.325 0.320 0.325 0.320 0.325 0.320 0.315 0.200 400 600 800 1000 Forward Current [mA]

Radiation Diagram 90 100 80 110 70 1.0 60 120 0.9 130 50 0.8 140 0.7 40 0.6 30 150 0.5 0.4 160 20 0.3 0.2 170 10 0.1 ł ÷ 0.0 - 180 0 Y

Y

Spectrum



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5. Soldering Profile

Reflow Soldering Conditions/ Profile

- (1) Lead Solder
 - Preliminary heating to be at 150 °C max. for 2 minutes max.
 - Soldering heat to be at 240 ℃ max. for 5 seconds max.



(2) Lead-Free Solder

- Preliminary heating to be at 150 $^\circ\!\!\!\mathrm{C}$ max. for 2 minutes max.
- \bullet Soldering heat to be at 260 $^\circ C$ max. for 10 seconds max.



(3) Hand Soldering Condition

• Not more than 1 seconds @MAX280°C, under Soldering iron.

[Note] In case the soldered products are reused in soldering process, Seoul Semiconductor can not guarantee the performance of the products.



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Tolerance: ±0.1, Unit: mm



* Recommend solder pad pattern



6. Outline Demension





Soldering Area

Heat dissipation Area (Cu)

7. Reel Dimension

Tolerance: ±0.2, Unit: mm

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1) Quantity : 2000pcs/Reel

2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2 \text{mm}$

3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at 10 $^\circ\!C$ angle to be the carrier tape

4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

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8. Precaution for Use

1. Storage

To avoid absorption of moisture, it is recommended to store parts in a dry box (or desiccator) with a desiccant. Otherwise, storage in the following environment is recommended. Temperature : $5^{\circ}C \sim 30^{\circ}C$ Humidity : 60%HR max.

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- Parts stored more than one week after opening or if desiccant indicator shower color changes, it is highly recommended that LED's should be baked for 10~ 12 hours at 60°C±5°C
- 3. LEDs must be stored at clean atmosphere. If the LEDs are stored for 3 months or more after shipment from SSC, storage in a sealed container with a nitrogen is recomented.
- 4. If the LED is considered to be wet, it is highly recommended that the LED should be dried for 100Hr at $80\pm5^{\circ}$ or 12Hr at $100\pm5^{\circ}$.
- 5. Any mechanical force or excess vibration should be avoided during temperature cooling process to normal temperature after reflow
- 6. Rapid cooling should be avoided
- 7. LED should not be placed on a flexible area of the PCB
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc.
 When washing is required, IPA should be used.
- 9. When the LED is operating in DC mode, the driving current should be determined after considering the thermal properties of the application and maximum ambient temperature requirements
- 10. Damage prevention from ESD or Surge.
 - 1. It is highly recommended to use the wrist-band or anti electrostatic gloves when handling the LED's
 - 2. All devices, equipments and machines mush be properly grounded

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